PERMABOND® ET5012

Two-Part Epoxy

Provisional Technical Datasheet

Features & Benefits

- Colourless
- Full cure at room temperature
- Adhesion to a variety of substrates
- Good flow properties

Description

PERMABOND® ET5012 is a two-part colourless epoxy adhesive which bonds to a wide variety of substrates such as wood, metal, ceramics and some plastics and composites. It cures at room temperature to give handling strength in approximately 20 minutes. This product is ideal for general purpose bonding and is suitable for applications that require a clear bond line.

Physical Properties of Uncured Adhesive

	ET5012A	**ET5012B**
Chemical composition	Epoxy Resin	Mercaptan Hardener
Appearance	Colourless	Colourless
Viscosity @ 25°C	70,000-80,000 mPa.s *(cP)*	15,000-25,000 mPa.s *(cP)*
	Mixed: 43,000-63,000 mPa.s *(cP)*	
Specific gravity	1.2	1.1

Typical Curing Properties

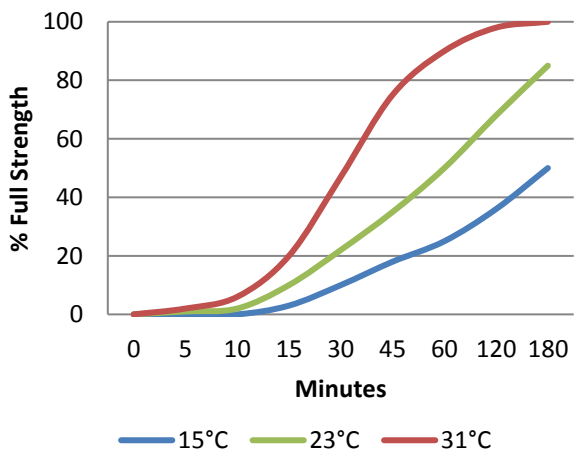
Mix ratio	1:1 by volume 100:94 by weight
Maximum gap fill	2 mm *0.08 in*
Usable / pot life @23°C 2g mixed	10-15 mins
Handling time @23°C	15-25 mins
Working strength @23°C	30 mins
Full cure @23°C	24 hours

Typical Performance of Cured Adhesive

Shear strength (mild steel)* (ISO4587)	6-12 N/mm² *(900 – 1700 psi)*
Peel strength (aluminium) (ISO4578)	5-20 N/25mm *(1-4 PIW)*
Hardness (ISO868)	70-80 Shore D
Elongation at break (ISO37)	<5%
Glass transition temperature Tg	40-50°C *(104-122°F)*
Dielectric strength	15-25 kV/ mm
Thermal conductivity	0.22 W/(m.K)

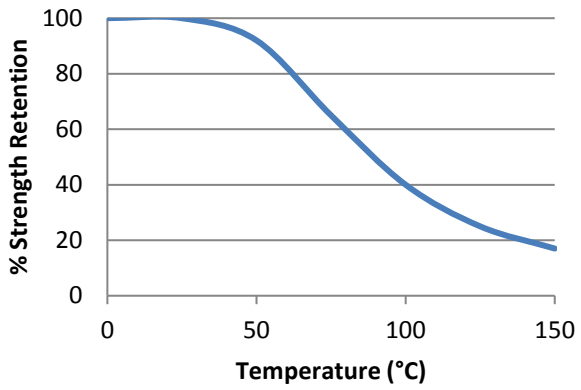
**Strength results will vary depending on the level of surface preparation and gap.*

Strength Development



Graph shows typical strength development of bonded components. An increase of 8°C in temperature will halve the cure time. Lower temperatures will result in a slower cure time.

Hot Strength



"Hot strength" shear strength tests performed on mild steel. Fully cured specimens conditioned to pull temperature for 30 minutes before testing at temperature.

ET5012 can withstand higher temperatures for brief periods (such as for paint baking and wave soldering processes) providing the joint is not unduly stressed. The minimum temperature the cured adhesive can be exposed to is -40°C (-40°F) depending on the materials being bonded.

Additional Information

This product is not recommended for use in contact with strong oxidizing materials.
Information regarding the safe handling of this material may be obtained from the safety data sheet.

Users are reminded that all materials, whether innocuous or not, should be handled in accordance with the principles of good industrial hygiene.

Surface Preparation

Surfaces should be clean, dry and grease-free before applying the adhesive. Use a suitable solvent (such as acetone or isopropanol) for the degreasing of surfaces. Some metals such as aluminium, copper and its alloys will benefit from light abrasion with emery cloth (or similar), to remove the oxide layer.
This Technical Datasheet (TDS) offers guideline information and does not constitute a specification.

Directions for Use

1. Dual cartridges:
   a) Insert the cartridge into the application gun and guide the plunger into the cartridge.
   b) Remove the cartridge cap and dispense material until both sides are flowing.
   c) Attach the static mixer to the end of the cartridge and begin dispensing the material.
2. Apply material to one of the substrates.
3. Join the parts. Parts must be joined within 10 minutes of mixing the two epoxy components.
4. Large quantities and/or higher temperature will decrease the usable life or pot life.
5. Apply pressure to the assembly by clamping for at least 15 minutes or until handling strength is obtained.
6. Full cure will be obtained after 24 hours at 23°C. Heat can be used to accelerate the curing process.

NB. Exercise caution when mixing large quantities due to exothermic reaction.

Video Links

Surface preparation:
https://youtu.be/8CMOMP7hXjU

Two-part epoxy directions for use:
https://youtu.be/GRX1RyknYqc

Storage & Handling

Storage Temperature	5 to 25°C *(41 to 77°F)*